



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Cheng-Lien Chiang  
Assignee: Bridge Semiconductor Corporation  
Title: THREE-DIMENSIONAL STACKED SEMICONDUCTOR  
PACKAGE DEVICE WITH BENT AND FLAT LEADS AND  
METHOD OF MAKING SAME  
Serial No.: 10/695,564 Filed: October 28, 2003  
Examiner: Williams, A. Group Art Unit: 2826  
Atty. Docket No.: BDG005-6

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*700 Sheet*

COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE**

In response to the Office Action dated August 31, 2004, please amend the application as follows.

The Title Amendments begin at page 2.

The Specification Amendments begin at page 3.

The Claim Amendments begin at page 6.

The Remarks begin at page 31.

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